REMARKS

In the Office Action of January 6, 2005, the Examiner rejected Claims 1-3, 6 and 8 under 35 U.S.C. §102(b) as being anticipated by the JP-359227143A (the "JP'143") reference. Additionally, the Examiner rejected Claims 9 and 15 under 35 U.S.C. Section 102(b) as being anticipated by the Bolken reference. Finally, Claims 4 and 5 were rejected under 35 U.S.C. Section 103(a) as being unpatentable over the JP '143 reference. Importantly, the Examiner indicated that Claims 7 and 10-14 were objected to as being dependent upon a respective base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening Claims.

Independent Claims 1 and 8 Are Not Anticipated by the JP '143 Reference:

Applicant respectfully submits that independent Claims 1 and 8, in their originally filed form, are not anticipated by the JP '143 reference. In its current form, independent Claim 1 states:

> *...each of the contacts of the leadframe being exposed in the bottom surface of the body and including a chamfer portion which extends to one of the lateral sides thereof.*

Similarly, in its current form, independent Claim 8 states:

> *...forming each of the contacts to include a chamfer portion which extends to one of the lateral sides of the body and a bottom surface which extends to the chamfer portion and is exposed in the bottom surface of the body.*

In the Office Action, the Examiner makes specific reference to Figures 4, 7(a), 7(b) and 11(a) of the JP '143 reference as purportedly satisfying all the features recited in Claims 1 and 8. Firstly, it must be noted that the JP '143 reference is not primarily directed to a memory card, but rather is directed only to a sub-assembly for later incorporation into an IC card, such sub-assembly including two rows of leads which are extended along respective ones of an opposed pair of sides of a die pad 2a having a semiconductor die 1 mounted thereto. As is most apparent from Figures 7(a) and 7(b) of the JP '143 reference, the semiconductor die 1 is mounted to the die pad 2a and electrically connected to each of the leads of the two rows thereof through the use of conductive wires. Each of the leads includes a central outwardly bent portion which defines a land 2c. The lands 2c defined by the bent portions of the leads are exposed in a common surface of a package body 3 which partially encapsulates the leads, and fully encapsulates the die pad 2a to which the semiconductor die 1 is mounted and the conductive wires used to electrically connect the semiconductor die 1 to the leads.

In addition to the central bent portion which defines the land 2c thereof, each lead defines a distal portion 2b which protrudes perpendicularly from a side surface of the package body 3. The region of each lead which defines the transition between the central bent portion and the distal portion 2b thereof is completely covered by the package body 3 as is clearly seen in Figures 7(a) and 7(b). Thus, only part of the distal portion 2b of each lead protrudes perpendicularly from a side surface of the package body 3.

In stark contrast to the teachings of the JP '143 reference, in the language of independent Claims 1 and 8 highlighted above, the chamfer portion of each of the contacts is described as extending to one of the lateral sides of the body. In the specification of the present application, the chamfer surface 32 of the chamfer portion 28 of each contact 16 is described as extending at a prescribed angle relative to the bottom surface 30 of the base portion 26 of such contact 16 (see specification, Paragraph 19). This angled relationship is also clearly shown in Figures 1 and 2 of the present application. The motivation for extending the chamfer portion 28 of each contact 16 to one of the lateral sides of the body is discussed in Paragraphs 22 and 23 of the specification of the present application. More particularly, the extension of the chamfer portion 28 of each of the contacts 16 to a common lateral side of the memory card body allows the connector pins of the host socket into which the memory card is inserted to hit only metal (i.e., the contacts 16 themselves), and thus avoids the rubbing of the connector pins of the host socket over any portion of the body of the memory card.

The same simply does not hold true for the sub-assembly disclosed in the JP '143 reference. Firstly, since the device disclosed in the JP '143 reference is a sub-assembly for later incorporation into an IC card as indicated above, such sub-assembly as shown in Figures 7(a) and 7(b) of the JP '143 reference would not and could not be advanced into a host socket including connector pins. Indeed, even if such advancement could occur, the connector pins of such host socket would still necessarily travel over portions of the package body 3 prior to coming in contact with the lands 2c since, as also indicated above, the central bent portion of each lead other than for the land 2c defined thereby is covered by the package body 3. In Figures 7(a) and 7(b) of the JP '143 reference, that portion of each lead arguably most analogous to the chamfer portion recited in Claims 1 and 8 is that section or segment of the central bent portion which extends between the land 2c and distal portion 2b. However, such segment of the central bent portion does not extend to and is not exposed in the side surface of the package body 3, but rather is completely covered thereby. As a result, a rail segment of the package body 3 extends between the side surface thereof and the land 2c, an occurrence which the present invention is specifically adapted to avoid. There would simply be no basis to modify the sub-assembly of the JP '143 reference to eliminate the rail segment of the package body 3 since such sub-assembly standing alone is clearly not intended to be advanced into a host socket including connector pins.

Thus, based on the foregoing, Applicant respectfully submits that independent Claims 1 and 8 in their current form are clearly not anticipated by the JP '143 reference, and are in condition for allowance. Additionally, Applicant respectfully submits that Claims 2-7 are also in condition for allowance as being dependent upon an allowable base claim (i.e., Claim 1).

Independent Claim 9 Is Not Anticipated by the Bolken Reference:

Referring now to the Section 102(b) rejection of independent Claim 9, Applicant respectfully submits that Claim 9 as originally filed is not anticipated by the cited Bolken reference. In its current form, Claim 9 states:

> *...the memory card including a means for preventing the connector pins from contacting the body upon the insertion of the memory card into the host socket connector.*

The connector pins recited in Claim 9 are a feature of the host socket connector into which the memory card is to be inserted. Neither Figures 1-4 of the Bolken reference (specifically referenced by the Examiner) or any passage of the specification thereof teaches or suggests the inclusion of any feature whatsoever in the card 10 of the Bolken reference which is adapted to prevent the connector pins of a host socket connector from contacting the body 28 of the card 10 when the same is advanced into the host socket connector.

In the Bolken reference, the card 10 is described as including a first molded plastic casting or body 26 which is molded onto the circuit side 16 of a substrate 12 to encapsulate a semiconductor component 14 mounted thereto. A second molded plastic casting or body 28 is described as surrounding the body 26 and enclosing the peripheral edge 30 of the substrate 12 to comprise exterior portions of the card 10. The body 28 is described as defining a peripheral edge 50 of the card 10 which has rounded corners 49 and a chamfered corner 98. In the Bolken reference, the chamfered corner 98 is described as being used to generally identify the end of the card 10 having external contacts 24 to ensure that a user inserts the card 10 in a proper orientation (column 6, lines 46-49). The contacts 24 are themselves exposed in a backside surface 22 of the card 10. As is clearly shown in Figures 3 and 4 of the Bolken reference, the contacts 24 do not include any chamfer portion whatsoever, and clearly do not extend to the peripheral edge 50 of the card 10. Rather, the reference numeral 22 shown in Figure 4 includes a leader line which extends to a rail segment of the body 28 which actually extends between the contacts 24 and the peripheral edge 50.

It is clear from the teachings of the Bolken reference, that the advancement of the card 10 into a host socket connector will result in the connector pins of such host socket connector traveling over the rail segment defined by the body 28 prior to coming into electrical communication with the contacts 24. Thus, Applicant respectfully submits that the Bolken reference is clearly devoid of any teaching or suggestion regarding the inclusion in the card 10 of a means for preventing the connector pins of the host socket connector from contacting the body 28 upon the insertion of the card 10 into a host socket connector. Accordingly, Applicant respectfully submits that independent Claim 9 in its original form is in condition for allowance, as are Claims 10-15 as being dependent upon an allowable base claim.

On the basis of the foregoing, Applicant respectfully submits that the stated grounds of rejection have been overcome, and that Claims 1-15 are now in condition for allowance. An early Notice of Allowance is therefore respectfully requested.

If any additional fee is required, please charge Deposit Account Number 19-4330.

Respectfully submitted,

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